

IN THE CLAIMS

Please cancel claims 55-58, 60-63, and 65-67 without prejudice.

Please amend claims 54, 59, and 64.

Please add new claims 68-79.

Please enter the following pending claims:

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54. (Currently Amended) A polish pad comprising:

~~a pad center area, said pad center area corresponding to a wafer center area;~~  
a first set of grooves disposed in ~~said pad center~~ a first area, said first set of grooves having a first depth;

~~a pad edge area disposed adjacent to said pad center area, said pad edge area corresponding to a wafer edge area; and~~

a second set of grooves disposed in ~~said pad edge~~ a second area, said second set of grooves having a second depth, wherein said first depth is smaller than said second depth to reduce polish rate in said first area.

55.-58. (Canceled)

59. (Currently Amended) A polish pad comprising:

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~~a pad center area, said pad center area corresponding to a wafer center area;~~  
a first set of grooves disposed in ~~said pad center~~ a first area, said first set of grooves having a first width;

~~a pad edge area disposed adjacent to said pad center area, said pad edge area corresponding to a wafer edge area; and~~

a second set of grooves disposed in ~~said pad edge~~ a second area, said second set of grooves having a second width, wherein said first width is smaller than said second width to reduce polish rate in said first area.

60.-63. (Canceled)

64. (Currently Amended) A polish pad comprising:

~~a pad center area, said pad center area corresponding to a wafer center area;~~  
a first set of grooves disposed in ~~said pad center~~ a first area, said first set of grooves having a first density;

~~a pad edge area disposed adjacent to said pad center area, said pad edge area corresponding to a wafer edge area; and~~

a second set of grooves disposed in ~~said pad edge~~ a second area, said second set of grooves having a second density, wherein said first density is smaller than said second density to reduce polish rate in said first area.

65.-67. (Canceled)

68. (New) The polish pad of claim 54 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

69. (New) The polish pad of claim 54 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

70. (New) The polish pad of claim 54 wherein said first area is disposed in a center of said polish pad.

71. (New) The polish pad of claim 54 wherein said first area is disposed at edges of said polish pad.

72. (New) The polish pad of claim 59 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

73. (New) The polish pad of claim 59 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

74. (New) The polish pad of claim 59 wherein said first area is disposed in a center of said polish pad.

75. (New) The polish pad of claim 59 wherein said first area is disposed at edges of said polish pad.

<sup>84</sup>  
76. (New) The polish pad of claim 64 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

<sup>85</sup>  
77. (New) The polish pad of claim 64 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

<sup>86</sup>  
78. (New) The polish pad of claim 64 wherein said first area is disposed in a center of said polish pad.

<sup>87</sup>  
79. (New) The polish pad of claim 64 wherein said first area is disposed at edges of said polish pad.

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